Reg	istra	ion No :								
Total Number of Pages : 02										
210		8 th Semester Regular / Back Examination 2017-18 MICRO ELECTRO MECHANICAL SYSTEMS BRANCH: AEIE, BIOMED, CSE, ECE, EIE, ETC, IEE, IT, ITE, MANUFAC, MANUTECH, MECH Time: 3 Hours Max Marks: 70 Q.CODE: C296 Inswer Question No.1 which is compulsory and any five from the rest. The figures in the right hand margin indicate marks.	EI5405							
Q1.		Answer the following questions : (2	x 10)							
	a)	What is SOC?								
	b)	List the type of microsystem packages.								
210	c)	What are the relative merits of MEMS varactors over its semiconductor counterpart?		4						
	d)	What do you mean by LPCVD?								
	e)									
	f) It takes a force of 20 millinewtons to hold a spring stretched to a distance of 40 micrometer. What is the elastic potential energy of the spring at this position?									
210	g)	What is Lab-on-a-chip? 210 210 210		2						
	h)	What is Coriolis force?								
	i)	Will the gain of a MEMS RF Resonator Oscillator improve if it operates under partial vacuum? Explain your answer in brief.								
	j)	What is the working principle of capacitive accelerometer?								
Q2.	a)	What is the primary reason of designing solenoid type MEMS inductor? Write down the diminutions and specifications of a typical MEMS solenoid inductor.	(5)							
	b)	Write down the relationship between the contact angle and the applied voltage in case of electro wetting based fluid flow. Define the terms.	(5)							
Q3.	a)	Explain the design considerations of peezoresistive pressure sensors.	(5)							
	b)	How many types of MEMS microlense do you know? Explain their design	(5)							
210		eatures. 210 210 210 210 210 210		-						
Q4.	a)	Compare surface and bulk micromachining techniques in MEMS.	(5)							
	b)	·	(5)							

(5)

(5)

Explain the special issues in microsystem packaging.

Explain the basic mechanical building blocks of MEMS system briefly.

Q5. a)

b)

10	210		210	210	210	210	210	210
	Q6. Q7.		Calculate the strain energy Narrate the process step How does an MEMS of	s involved in phot gyroscope work?	olithography. Define coriolis	force and corio	(5) (5) lis (10)	210
	2.0		acceleration. Discuss the fabricating the gyroscope	ne compensatior e. Also explain the	n techniques us e meaning of DSA	sed in process A.	of	2.0
	Q8.	a) b)	Write Short Notes any Tory etching Pull-in voltage	Γ W O :			(5 x 2)	
10	210	•	Mechanical actuators LIGA	210	210	210	210	210
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